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- (71) Applicant: **APPLIED MATERIALS, INC.** [US/US];
3050 Bowers Avenue, Santa Clara, California 95054 (US).
- (72) Inventors: **ADERHOLD, Wolfgang, R.**; c/o Applied Materials, Inc., Law Dept., M/s 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US). **IU, Dongming**; c/o Applied Materials, Inc., Law Dept., M/s 1269, 3050 Bowers Avenue, Santa Clara, California 95054 (US).

(74) Agent: **DOUGHERTY, Chad, M.** et al.; PATTERSON + SHERIDAN LLP, 24 Greenway Plaza, Suite 1600, Houston, Texas 77046 (US).

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(54) Title: ROTATABLE THERMAL PROCESSING CHAMBER

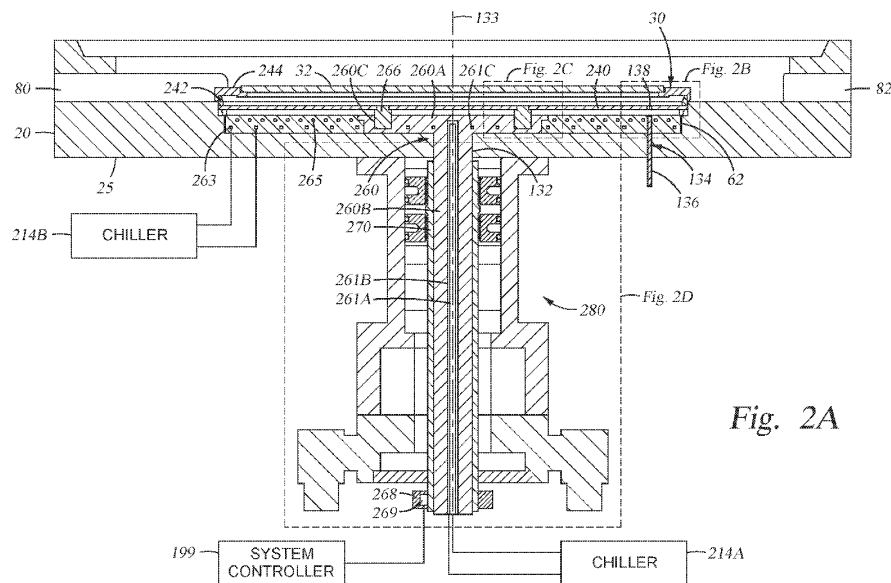


Fig. 2A

(57) Abstract: The present disclosure relates to heating a substrate in a rapid thermal processing (RTP) chamber. The chamber may contain a rotatable assembly configured to accommodate and rotate the substrate while a heat source inside the RTP chamber applies heat to the substrate. The rotatable assembly is partially disposed outside the RTP chamber. A seal may be formed around the rotatable assembly and maintain a vacuum inside the RTP chamber while the rotatable assembly rotates. The rotatable assembly may be configured to accommodate various-sized substrates.

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